Data Sheet

Product Description
DuPont™ SAC™ EKC652™ semi-aqueous chemistry remover is an advanced chemistry formulation that removes post-etch residue quickly and effectively from substrates containing traditional integration materials.

Application
EKC652™ is specifically designed to remove Post-etch residue from traditional integration materials in either wet bench or batch spray operation. It enables high yield production of 250nm and below semiconductor devices.

Product Performance
- Ideally suited for devices with critical dimensions ≤250nm
- Compatible with a variety of traditional integration materials
- Good bath life and low Cost of Ownership
- Operates well in a variety of equipment, wet bench or batch spray
- Enables processing through improved device electrical performance
- Smaller environmental footprint solution

Before cleaning with DuPont™ SAC™ EKC652™ semi-aqueous chemistry remover

After cleaning with DuPont™ SAC™ EKC652™ semi-aqueous chemistry remover (8min, 20°C)
For more information on DuPont™ SAC™ semi-aqueous chemistry removers or other DuPont EKC Technology products, please contact your local representative, or visit our website:

**Americas**
DuPont Electronic Technologies
EKC Technology, Inc.
2520 Barrington Court
Hayward, CA 94545
Tel: 510 784 9105

**Japan**
EKC Technology, K.K.
KSP R&D D3 42
3-2-1 Sakado, Takatsu-ku, Kawasaki
Kanagawa, 213-0012 Japan
Tel: 81 44 850 8215

**Taiwan**
EKC Technology
No. 2, LiHsing 4th Road
Science-Based Industrial Park
Hsinchu, Taiwan R.O.C.
Tel: 866 357 90550
Fax: 866 357 98857

**European Sales & Support**
EU Technical Support: 44 (0) 16 98 26 69 46
EU Sales Support: 44 (0) 15 55 72 80 84
EU Fax: 44 (0) 13 13 41 10 43

www.ekctech.com

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Caution: Do not use in medical applications involving permanent implantation in the human body. For other medical applications, see “DuPont Medical Caution Statement: H-81469 or H-80102-2”